

ABSTRACT OF DISCLOSURE

A leadless plastic chip carrier is fabricated by partially etching at least a first surface of a leadframe strip to partially define a die attach pad, a plurality of contact pads disposed around the die attach pad, and a plurality of bond fingers intermediate the die attach pad and the contact pads. A metal strip is laminated to the first surface of the leadframe strip. A second surface of the leadframe strip is selectively etched such that portions of the leadframe strip are removed to define a remainder of the die attach pad, the plurality of contact pads, the plurality of bond fingers and circuitry between ones of the bond fingers and ones the contact pads. A semiconductor die is mounted to the die attach pad and wire bonds connect the semiconductor die to ones of the bond fingers. The second surface of the leadframe strip, the semiconductor die and the wire bonds are encapsulated in a molding material. The metal strip is removed from the first surface of the leadframe strip and the leadless plastic chip carrier is singulated from a remainder of the leadframe strip.